

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	0.63481	100.0	10
			Subtotal	0.63481	100	10
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01485	0.04	0.234
	Copper alloy	Iron (Fe)	7439-89-6	0.03714	0.1	0.585
	Copper alloy	Copper (Cu)	7440-50-8	37.08412	99.86	584.181
			Subtotal	37.13611	100	585
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.77378	4.5	43.695
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.16396	10.0	97.1
	Filler	Silica fused	60676-86-0	46.22969	75.0	728.25
	Metal hydroxide	Metal hydroxide		6.16396	10.0	97.1
	Carbon Black	Carbon black	1333-86-4	0.3082	0.5	4.855
			Subtotal	61.63959	100	971
Die		Lead Dioxide (PbO2)	1309-60-0	0.00228	1.06	0.03586
		Silicon (Si)	7440-21-3	0.21249	98.94	3.3473
			Subtotal	0.21477	100	3.38316
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.20314	100.0	3.2
			Subtotal	0.20314	100	3.2
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00858	5.0	0.13516
	Lead alloy	Silver (Ag)	7440-22-4	0.00429	2.5	0.06758
	Lead alloy	Lead (Pb)	7439-92-1	0.15873	92.5	2.5004
			Subtotal	0.1716	100	2.70314
			Total	100.00002	100	1575.2863

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